SN75151 QUADRUPLE DIFFERENTIAL LINE DRIVER

SLLS082B - DECEMBER 1978 - REVISED MAY 1995

 Meets or Exceeds the Requirement of ANSI EIA/TIA-422-B 	DW OR N PACKAGE (TOP VIEW)
 High-Impedance Output State for Party-Line Operation 	1A [1 20] V _{CC}
 High Output Impedance in Power-Off Condition 	1Y [] 2 19 [] 4A 1Z [] 3 18 [] 4Y
Low Input Current to Minimize Loading Single 5 V Supply	1C 4 17 4Z CC 5 16 4C
Single 5-V Supply40-mA Sink- and Source-Current Capability	2C [6 15] S 2Z [7 14] 3C
High-Speed Schottky Circuitry	2Y 🛮 8 13 🖸 3Z
Low Power Requirements	2A [] 9 12 [] 3Y GND [] 10 11 [] 3A

description

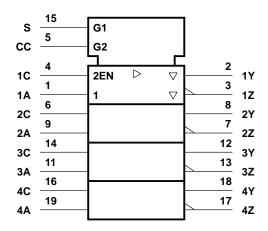
This line driver is designed to provide differential signals with high current capability on balanced lines. This circuit provides strobe and enable inputs to control all four drivers and provides an additional enable input for each driver. The output circuits have active pullup and pulldown resistors and are capable of sinking or sourcing 40 mA.

The SN75151 meets all requirements of ANSI EIA/TIA-422-B and Federal Standard 1020. The SN75151 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

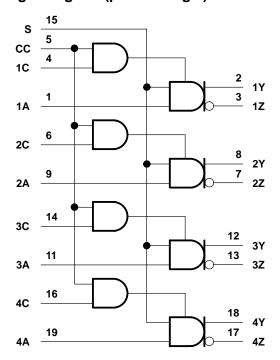
	INPUTS					OUTPUTS	
Е	NABLE CC	ENABLE C	STROBE S	DATA A	Y	Z	
	L	Х	Х	Х	Z	Z	
	X	L	Χ	Χ	Z	Z	
	Н	Н	L	Χ	L	Н	
	Н	Н	Χ	L	L	Н	
	Н	Н	Н	Н	Н	L	

logic symbol†

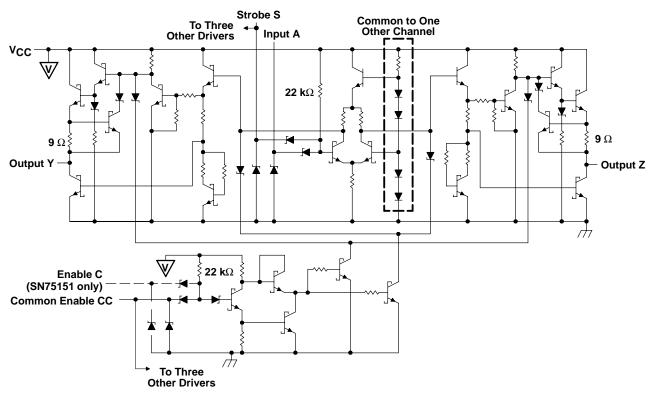


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic



Resistor values shown are nominal.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Input voltage, V _I	5.5 \
Continuous total dissipation	
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	

NOTE 1: All voltage values, except differential output voltage V_{OD}, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE T _A ≤ 25°C POWER RATING		OPERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
DW	1125 mW	9.0 mW/°C	720 mW		
N	1150 mW	9.2 mW/°C	736 mW		

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
High-level input voltage, V _{IH}	2			V
Low-level input voltage, V _{IL}			0.8	V
Common-mode output voltage, VOC	-0.25		6	V
High-level output current, IOH			-40	mA
Low-level output current, IOL			40	mA
Operating free-air temperature, T _A	0		70	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]		MIN	TYP [‡]	MAX	UNIT
V	lanut alama valtana	CC, S	CC, S			-2	V
VIK	Input clamp voltage	$V_{CC} = MIN, I_I = -12 \text{ mA}$	All others		-0.9	-1.5	V
		V _{CC} = MIN, V _{IL} = MAX,	$I_{OH} = -20 \text{ mA}$	2.5			.,
VOH	High-level output voltage	V _{IH} = 2 V	I _{OH} = - 40 mA	2.4			V
VOL	Low-level output voltage	$V_{CC} = MIN, V_{IL} = MAX,$ $I_{OL} = 40 \text{ mA}$	V _{IH} = 2 V,			0.5	٧
VOD1	Differential output voltage	$V_{CC} = MAX, I_{O} = 0$			3.4	2V _{OD2}	V
IVOD2l	Differential output voltage	V _{CC} = MIN		2	2.8		V
ΔΙVODI	Change in magnitude of differential output voltage§	V _{CC} = MIN			±0.01	±0.4	٧
V		VCC = MAX	R_L = 100 Ω, See Figure 1		1.8	3	W
Voc	Common-mode output voltage¶	V _{CC} = MIN	See rigure r		1.6	3	V
∆lVocl	Change in magnitude of common- mode output voltage§	V _{CC} = MIN or MAX			±0.02	±0.4	٧
	Off-state (high-impedance-state) output current	V _{CC} = MAX, Enable at 0.8 V	V _O = 0.5 V			-20	
loz			V _O = 2.5 V			20	μΑ
			AO = ACC			20	
	Output current with power off		V _O = 6 V		0.1	100	μΑ
lO		ACC = 0	$V_0 = -0.25 \text{ V}$		-0.1	-100	
			$V_0 = -0.25 \text{ V to 6 V}$			±100	
ΙĮ	Input current at maximum input voltage	$V_{CC} = MAX$, $V_I = 5.5 V$				0.1	mA
ΊΗ	High-level input current	V _{CC} = MAX, V _I = 2.4 V	C(SN75151), A			20	Δ
HII		VCC = WAX, V = 2.4 V	CC, S			80	μΑ
IIL	Low-level input current	V _{CC} = MAX, V _I = 0.4 V	C(SN75151), A			-0.36	mA
·1L			CC, S			-1.6	,
los	Short-circuit output current#	V _{CC} = MAX		-50	-90	-150	mA
lcc	Supply current (both drivers)	V _{CC} = MAX, No load	Outputs disabled		30	60	mA
.00	Cappiy current (both univers)	- W. V., 140 load	Outputs enabled		60	80	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at T_A = 25°C and V_{CC} = 5 V except for V_{OC}, for which V_{CC} is as stated under test conditions.

[§] $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitudes of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level

In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage, VOS.

[#]Only one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	C _L = 30 pF,	R _L = 100 Ω,		15	30	ns
tPHL	Propagation delay time, high- to low-level output	Termination A,	A, See Figure 2		15	30	ns
^t PLH	Propagation delay time, low- to high-level output	$C_L = 30 pF,$	Termination B,		13	25	ns
tPHL	Propagation delay time, high- to low-level output	See Figure 2			13	25	ns
tTLH	Transition time, low- to high-level output	$C_{I} = 30 \text{ pF}, \qquad R_{I} = 100 \Omega,$	R _L = 100 Ω,		12	20	ns
tTHL	Transition time, high- to low-level output	Termination A,	See Figure 2		12	20	ns
^t PZH	Output enable time to high level	C _L = 30 pF, See Figure 3	$R_L = 60 \Omega$,		18	35	ns
tPZL	Output enable time to low level	C _L = 30 pF, See Figure 4	R _L = 111 Ω,		20	35	ns
tPHZ	Output disable time from high level	C _L = 30 pF, See Figure 3	$R_L = 60 \Omega$,		19	30	ns
tPLZ	Output disable time from low level	C _L = 30 pF, See Figure 4	$R_L = 111 \Omega$,		13	30	ns
	Overshoot factor	$R_L = 100 \Omega$, See Figure 2	Termination C,			10	%

[†] All typical values are at $T_A = 25$ °C.

PARAMETER MEASUREMENT INFORMATION

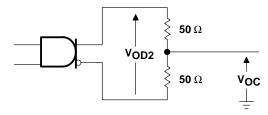
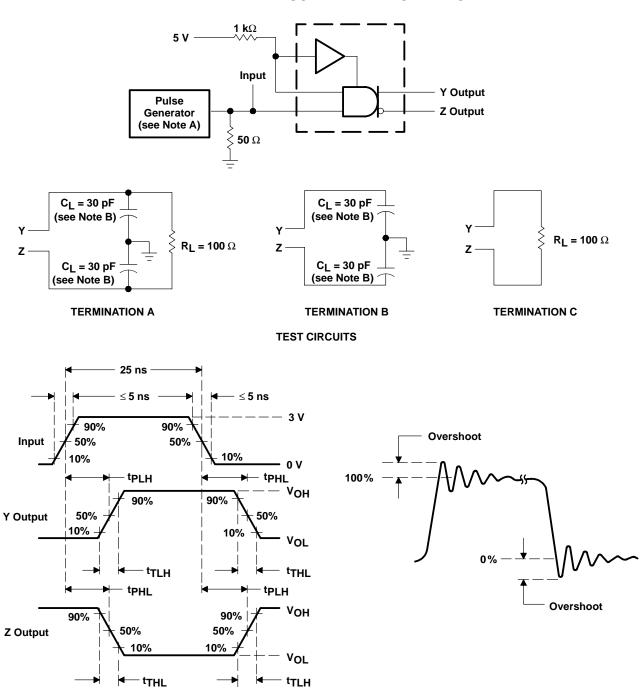


Figure 1. Differential and Common-Mode Output Voltages

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

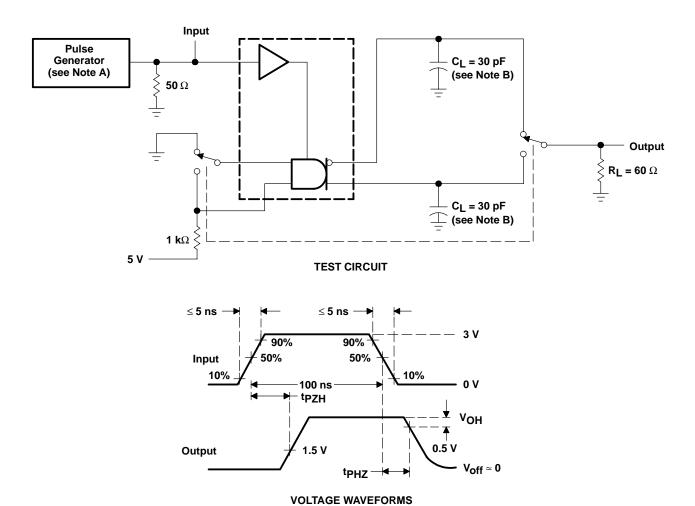
NOTES: A. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, PRR $\leq 10 \text{ MHz}$.

B. C_L includes probe and jig capacitance.

Figure 2. Test Circuits, Voltage Waveforms, and Overshoot Factor



PARAMETER MEASUREMENT INFORMATION

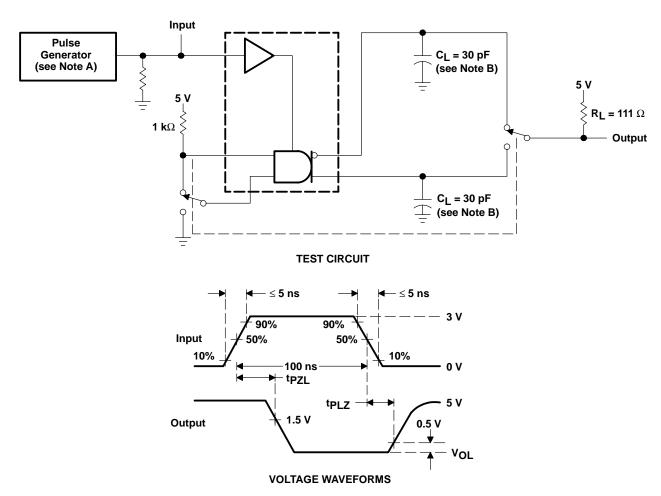


NOTES: A. The pulse generator has the following characteristics: Z_O = 50 Ω , PRR \leq 500 kHz.

B. C_L includes probe and jig capacitance.

Figure 3. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generators have the following characteristics: Z_0 = 50 Ω , PRR \leq 500 kHz.

B. C_L includes probe and jig capacitance.

Figure 4. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

Y OUTPUT VOLTAGE vs DATA INPUT VOLTAGE

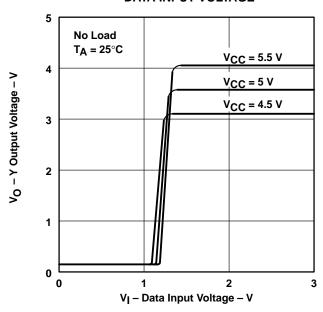
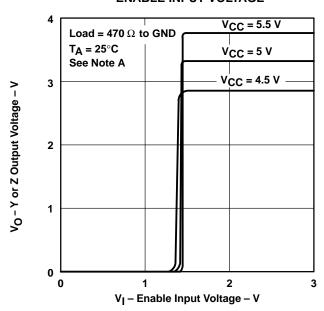


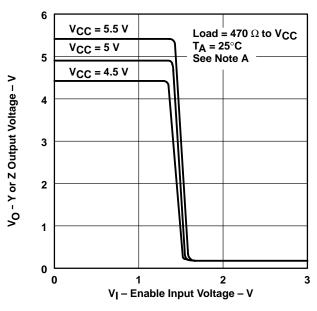
Figure 5

Y OR Z OUTPUT VOLTAGE vs ENABLE INPUT VOLTAGE



NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to ground during testing of the Z outputs.

Y OR Z OUTPUT VOLTAGE vs ENABLE INPUT VOLTAGE

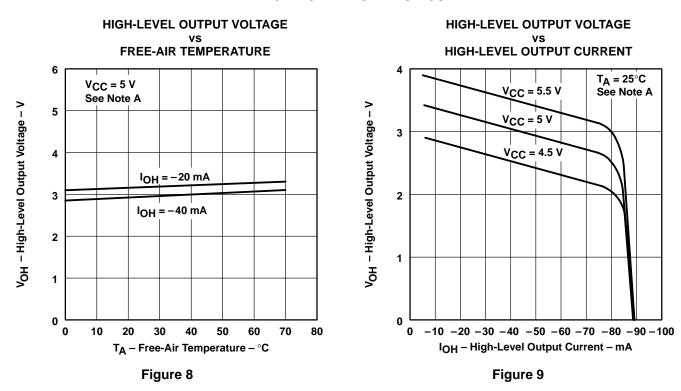


NOTE A: The A input is connected to GND during the testing of the Y outputs and to V_{CC} during the testing of the Z outputs.

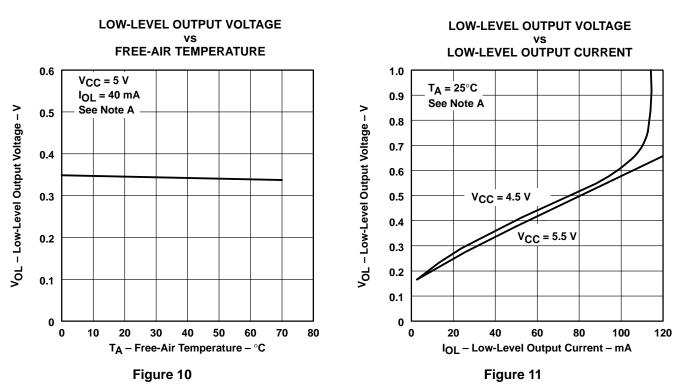
Figure 6 Figure 7



TYPICAL CHARACTERISTICS



NOTE A: The A input is connected to VCC during the testing of the Y outputs and to ground during testing of the Z outputs.

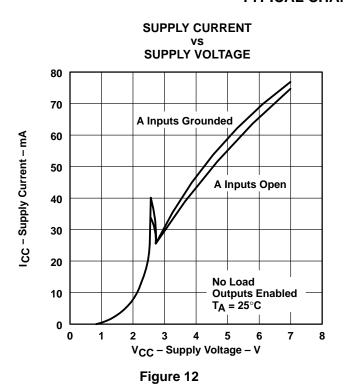


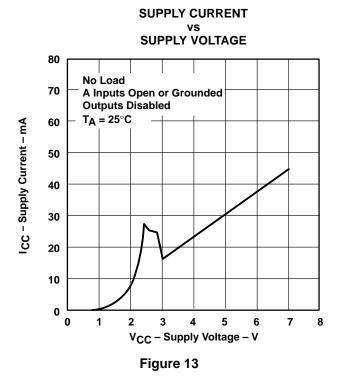
NOTE A: The A input is connected to GND during the testing of the Y outputs and to V_{CC} during the testing of the Z outputs.



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TYPICAL CHARACTERISTICS





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